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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)		Application Number	09/872,151-Conf. #9156		
		Filing Date	May 31, 2001		
		First Named Inventor	Kyle M. Hanson		
		An Unit	1741		
		Examiner Name	W. T. Leader		
Sheet	7	of	8	Attorney Docket Number	291958158US

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NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
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Examiner Signature	Donald R. Valentine		Date Considered 12/30/04